

IN THE CLAIMS

Please amend the claims as follows:

Claims 1-17 (Canceled).

Claim 18 (Currently Amended): A substrate processing apparatus, comprising:  
a carrier block including a carrier placement portion to/from which a substrate carrier storing a plurality of substrates is loaded/unloaded, and first transfer means for performing delivery of the substrate with respect to the substrate carrier placed on the carrier placement portion;  
second transfer means provided adjacent to the carrier block and for transferring the substrate along a linear transfer path extending in a lateral direction;  
a first delivery stage for performing delivery of the substrate between said first transfer means and said second transfer means;  
a plurality of process blocks each including a plurality of process units for performing predetermined processing on the substrate, third transfer means for transferring the substrate between [[the]] process units in each of the process blocks of the plurality of process blocks, and a second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, said plurality of process blocks being provided with respect to a main body of the apparatus to be arranged along said transfer path, and performing a series of substrate processing on the substrates in units of the plurality of process blocks;  
a process block control portion controlling operations of said third transfer means and the respective process units and outputting processing information of the substrates within the corresponding process block such that predetermined processing is performed on the substrates in each of the process blocks based on a predetermined recipe; and

means for determining a controller programmed to determine a process block where there is no substrate or where a final step for the last substrate within the relevant process block will be finished earliest based on the processing information of the substrates from the process block control portions before the substrate is delivered from the first delivery stage to the second transfer means, and for controlling the second transfer means to transfer the substrate on said first delivery stage to the relevant process block;

    said process block including a coating unit for applying a resist solution to the substrate, a developing unit for performing developing processing on the substrate after exposure to light, a heating unit for heating the substrate, the third transfer means for transferring the substrate between coating, developing, and heating the units, and the second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, and such application of the resist solution and/or the developing processing after exposure to light being performed on the substrate in units of each process block.

Claim 19 (Previously Presented): The substrate processing apparatus according to claim 18, wherein first and second lots containing a plurality of substrates are stored in said substrate carrier, and said means for controlling the second transfer means controls the second transfer means such that, when the last substrate in said first lot is being processed in one of said process blocks, if the other process block is not performing substrate processing, the first substrate in the second lot is transferred to that process block portion which is not performing the processing to allow the substrate to be processed in the relevant process block portion.

Claim 20 (Previously Presented): The substrate processing apparatus according to claim 18, wherein an interface portion to which a light exposure device is connected is connected to a side of said transfer path opposite to a side connected to the carrier block.

Claim 21 (Previously Presented): The substrate processing apparatus according to claim 18, wherein an interface portion to which a light exposure device is connected is connected to a side of said transfer path opposite to a side connected to the process blocks.

Claim 22 (Currently Amended): The substrate processing apparatus according to claim 18, wherein [[said]] each process block of the plurality of process blocks includes a plurality of the coating units, a plurality of the developing units, and a plurality of the heating units, and said process block control portion further includes a function to select the coating unit, the developing unit, and the heating unit for use in the processing based on the process recipe of the substrate.

Claim 23 (Previously Presented): The substrate processing apparatus according to claim 18, wherein each process block includes a liquid process unit performing processing on the substrate using a chemical solution, a heating unit for heating the substrate, the third transfer means for transferring the substrate between the units, and the second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, and a series of processing are performed on the substrate in units of each process block.

Claim 24 (Currently Amended): The substrate processing apparatus according to claim 23, wherein [[said]] each process block of the plurality of process blocks includes a

plurality of the liquid process units and a plurality of the heating units, and said process block control portion further includes a function to select the liquid process unit and the heating unit for use in the processing based on the process recipe of the substrate.

Claim 25 (Previously Presented): The substrate processing apparatus according to claim 23, wherein said liquid process unit is for forming a coating film.

Claim 26 (Previously Presented): The substrate processing apparatus according to claim 23, wherein said liquid process unit is for coating the substrate with a chemical solution containing a precursor of an insulating film.

Claim 27 (Previously Presented): The substrate processing apparatus according to claim 18, wherein said plurality of process blocks are formed to have the same size in two dimensions.

Claim 28 (Previously Presented): The substrate processing apparatus according to claim 18, wherein said second transfer means is provided at a transfer block that extends along an arrangement of the plurality of process blocks, and each process block is configured to be attachable to and detachable from the transfer block.

Claim 29 (Withdrawn): A substrate processing method, provided with first transfer means for performing delivery of a substrate with respect to a substrate carrier containing a plurality of substrates, second transfer means for performing delivery of the substrate with respect to the first transfer means via a first delivery stage, and a plurality of process blocks each including a plurality of process units for performing predetermined processing on the

substrate, third transfer means for transferring the substrate between the process units, and a second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, said process block including a coating unit for applying a resist solution to the substrate, a developing unit for performing developing processing on the substrate after exposure to light, a heating unit for heating the substrate, the third transfer means for transferring the substrate between the units, and the second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, and performing such application of the resist solution and/or the developing processing after exposure to light on the substrate in units of each process block, a series of substrate processing being performed in said process blocks with respect to the substrates in said substrate carrier in units of the process blocks, the method comprising:

the first transfer means transferring the substrate within the substrate carrier to the first delivery stage;

determining the process block where there is no substrate or where a final step for the last substrate within the relevant process block will be finished earliest, based on processing information of the substrates in the respective process blocks, before the second transfer means receives the substrate of the first delivery stage; and

subsequently, the second transfer means receiving the substrate placed on said first delivery stage and transferring the relevant substrate to said determined process block.

Claim 30 (Withdrawn): The substrate processing method according to claim 29, wherein said process block includes a plurality of the coating units, a plurality of the developing units, and a plurality of the heating units, and when the process block to which the substrate placed on said first delivery stage is to be transferred is determined, the coating unit, the developing unit, and the heating unit for performing the processing on said substrate are

selected in the relevant process block, and the application of the resist solution and/or the developing processing after exposure to light is performed on the substrate in units of each process block.

Claim 31 (Withdrawn): The substrate processing method according to claim 29, wherein each process block includes a liquid process unit performing processing on the substrate using a chemical solution, a heating unit for heating the substrate, the third transfer means for transferring the substrate between the units, and the second delivery stage for performing delivery of the substrate between said second transfer means and said third transfer means, and a series of processing are performed on the substrate in units of each process block.

Claim 32 (Withdrawn): The substrate processing method according to claim 31, wherein said process block includes a plurality of the liquid process units and a plurality of the heating units, and when the process block to which the substrate placed on said first delivery stage is to be transferred is determined, the liquid process unit and the heating unit for performing the processing on said substrate are selected in the relevant process block, and predetermined substrate processing is performed on the substrate in units of each process block.